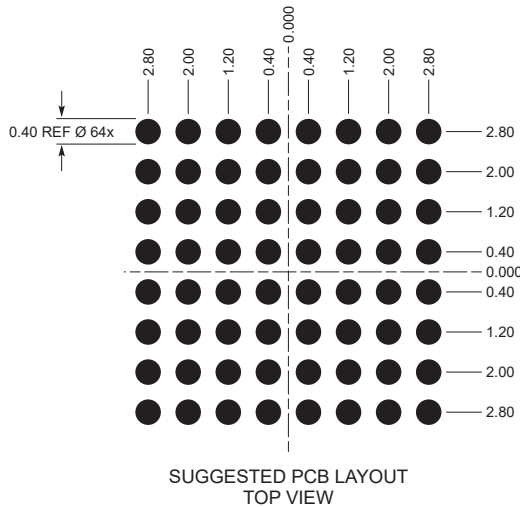
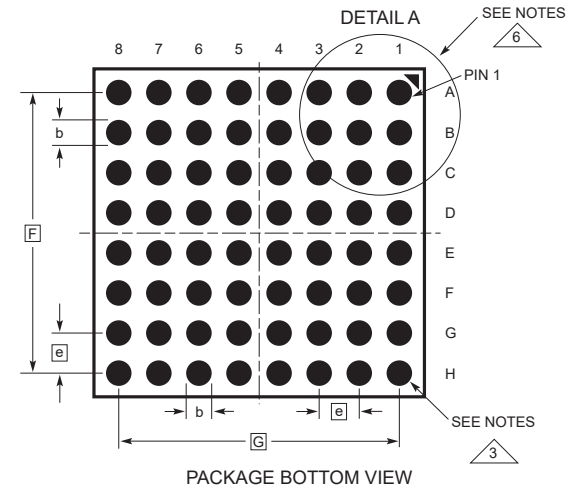
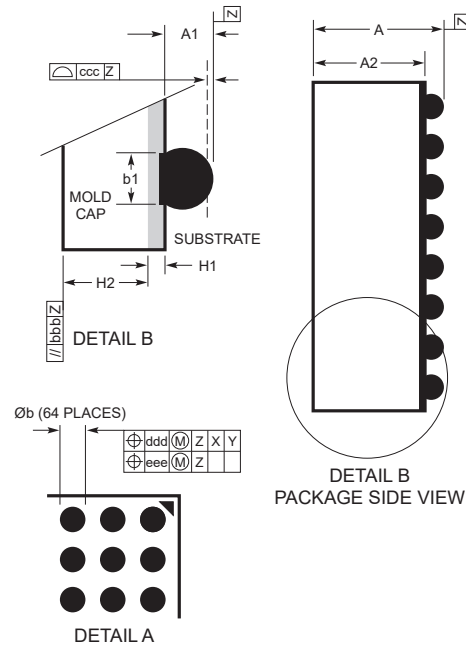
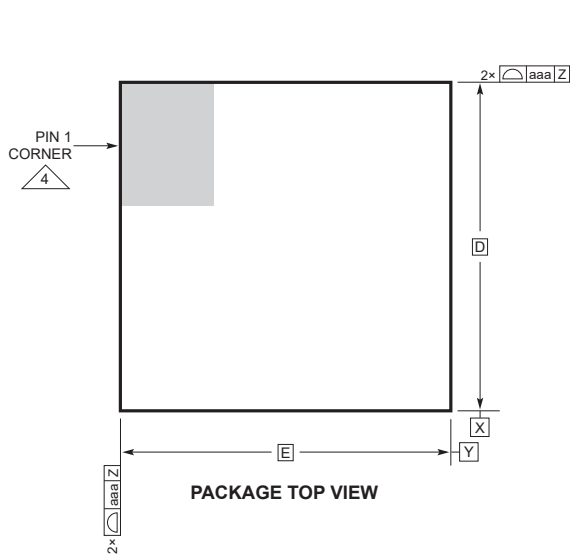


BGA Package
64-Lead (7.00mm × 7.00mm × 1.42mm)
 (Reference LTC DWG # 05-08-7086 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.23	1.42	1.61	
A1	0.30	0.40	0.50	BALL HT
A2	0.93	1.02	1.11	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D	7.00			
E	7.00			
e	0.80			
F	5.60			
G	5.60			
H1	0.32 REF		SUBSTRATE THK	
H2	0.70 REF		MOLD CAP HT	
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 64

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

